

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-54. (Canceled)

55. (Previously Presented) A substrate having penetrating holes formed therein, the substrate having a wiring pattern directly formed over a particular region including the penetrating holes on one side thereof, the substrate having protrusions formed in the internal wall surfaces of the penetrating holes by the material constituting the substrate.

56. (Canceled)

57. (Previously Presented) The substrate as defined in claim 55, wherein the adhesive material is an adhesive tape.

58. (Canceled)

59. (Previously Presented) The substrate as defined in claim 55, wherein the wiring pattern includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.

60. (Canceled)

61. (Previously Presented) The substrate as defined in claim 55, wherein the substrate is an insulating substrate.

62. (Canceled)

63. (Previously Presented) The substrate as defined in claim 55, wherein the substrate is a printed substrate.

64. (Canceled)

65. (Previously Presented) The substrate as defined in claim 55, further comprising an anisotropic conductive material having conductive particles dispersed in an adhesive.

66. (Previously Presented) A method of manufacturing a substrate comprising:
providing a substrate with an adhesive material provided on one surface thereof;
carrying out punching from the side of the substrate on which the adhesive material is provided and in the direction of the opposite side thereof to form penetrating holes and to draw a part of the adhesive material into the penetrating holes; and
adhering a wiring pattern over a particular region on the one surface including the penetrating holes on the substrate through the adhesive material.
67. (Previously Presented) A method of manufacturing a substrate comprising providing a substrate of a material of a higher elasticity than external electrodes, having penetrating holes in which the internal wall surfaces have protrusions, and having a wiring pattern directly formed over a region including the penetrating holes.
68. (Previously Presented) The method of manufacturing a substrate as defined in claim 67, wherein the penetrating holes are formed by a laser.
69. (Previously Presented) The method of manufacturing a substrate as defined in claim 67, wherein the penetrating holes are formed by wet etching.
70. (Previously Presented) The method of manufacturing a substrate as defined in claim 66, wherein the substrate is either of an insulating film or of printed substrate.
71. (Previously Presented) The method of manufacturing a substrate as defined in claim 67, wherein the substrate is either of an insulating film or of printed substrate.
72. (Previously Presented) The method of manufacturing a substrate as defined in claim 66, after adhering the wiring pattern, further comprising providing an adhesive in which an anisotropic conductive material having conductive particles are dispersed.

73. (Previously Presented) The method of manufacturing a substrate as defined in claim 67, after adhering the wiring pattern, further comprising providing an adhesive in which an anisotropic conductive material having conductive particles are dispersed.

74. (Previously Presented) A substrate comprising:

- a first side;
- a second side opposite the first side;
- penetrating holes extending through the substrate from the first side to the second side;
- a wiring pattern adhered to the second side of the substrate by an adhesive material over a particular region of the second side, the wiring pattern formed over the penetrating holes, a part of the adhesive material formed on internal wall surfaces forming the penetrating holes so as not to stop up the penetrating hole; and
- external electrodes contacting the wiring pattern and projecting through the penetrating holes from the second side of the substrate and extending beyond the first side of the substrate.

75. (Previously Presented) The substrate as defined in claim 74, wherein a part of the adhesive material enters and exists within the penetrating holes.

76. (Previously Presented) The substrate as defined in claim 74, wherein the adhesive material is an adhesive tape.

77. (Previously Presented) The substrate as defined in claim 74, wherein the wiring pattern includes first and second portions, a part of the first portion positioned over each of the penetrating holes, the first portion having a greater width than the second portion.

78. (Previously Presented) The substrate as defined in claim 74, wherein the substrate is an insulating substrate.

79. (Previously Presented) The substrate as defined in claim 74, wherein the substrate is a printed substrate.

80. (Previously Presented) The substrate as defined in claim 74, further comprising an anisotropic conductive material having conductive particles dispersed in an adhesive.